

**WHAT IS CLAIMED IS:**

1. A method for manufacturing a semiconductor device comprising steps of:

5       fixing semiconductor chips onto a substrate;  
      covering the semiconductor chips fixed onto the substrate with a common resin layer;  
      gluing an adhesive sheet onto the resin layer;  
      cutting the substrate and the resin layer in a state  
10   that the adhesive sheet is glued to the resin layer; and  
      measuring the semiconductor devices in a state that the adhesive sheet is glued to the resin layer.

2. A method for manufacturing a semiconductor device  
15 according to claim 1,

      wherein the substrate and the resin layer is cut from the reverse surface of the substrate in a state that the adhesive sheet is glued to the resin layer.

20       3. A method for manufacturing a semiconductor device according to claim 1,

      wherein the substrate and the resin layer which are cut are integrally supported by the adhesive sheet.

25       4. A method for manufacturing a semiconductor device

according to claim 1,

wherein the substrate and the resin layer is cut by performing dicing in a state that the adhesive sheet is glued to the resin layer.

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5. A method for manufacturing a semiconductor device according to claim 1,

wherein external electrodes are provided on the reverse surface of the substrate and electrically connected to the semiconductor chips.

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6. A method for manufacturing a semiconductor device according to claim 1, further comprising a step of:

flattening the surface of the resin layer after covering the semiconductor chips with the resin layer.

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7. A method for manufacturing a semiconductor device according to claim 1,

wherein the circumferential edge of the adhesive sheet is fixed to a metal frame.

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8. A method for manufacturing a semiconductor device according to claim 7,

wherein a plurality of the substrates are glued to the adhesive sheet.

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9. A method for manufacturing a semiconductor device according to claim 1, further comprising steps of:

fixing semiconductor chips onto a substrate;

5 covering the semiconductor chips fixed onto the substrate with a common resin layer;

gluing an adhesive sheet onto the resin layer;

cutting the substrate and the resin layer in a state that the adhesive sheet is glued to the resin layer;

10 measuring the semiconductor devices in a state that the adhesive sheet is glued to the resin layer;

peeling the resin layer from the adhesive sheet after performing the measurement of the semiconductor devices; and

15 directly storing the semiconductor device peeled from the adhesive sheet in a carrier tape.

10. A method for manufacturing a semiconductor device according to claim 9,

20 wherein the substrate and the resin layer is cut from the reverse surface of the substrate in a state that the adhesive sheet is glued to the resin layer.

11. A method for manufacturing a semiconductor device according to claim 9,

25 wherein the substrate and the resin layer which are cut

are integrally supported by the adhesive sheet.

12. A method for manufacturing a semiconductor device according to claim 9,

5 wherein the substrate and the resin layer is cut by performing dicing in a state that the adhesive sheet is glued to the resin layer.

10 13. A method for manufacturing a semiconductor device according to claim 9,

wherein external electrodes are provided on the reverse surface of the substrate and electrically connected to the semiconductor chips.

15 14. A method for manufacturing a semiconductor device according to claim 9, further comprising a step of:

flattening the surface of the resin layer after covering the semiconductor chips with the resin layer.

20 15. A method for manufacturing a semiconductor device according to claim 9,

wherein the circumferential edge of the adhesive sheet is fixed to a metal frame.

25 16. A method for manufacturing a semiconductor device

according to claim 10,

wherein a plurality of the substrates are glued to the adhesive sheet.

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